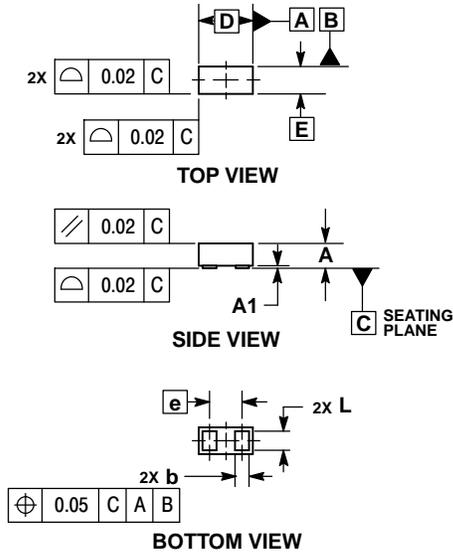




SCALE 12:1

**WLCSP2, 0.6x0.3**  
CASE 567AV  
ISSUE C

DATE 22 SEP 2017



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.250	0.275	0.300
A1	0.000	0.025	0.050
b	0.140	0.155	0.170
D	0.570	0.600	0.630
E	0.270	0.300	0.330
e	0.36 BSC		
L	0.190	0.215	0.240

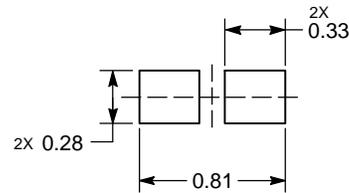
**GENERIC MARKING DIAGRAM\***



X = Specific Device Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

**RECOMMENDED SOLDER FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	WLCSP2, 0.6X0.3	<b>PAGE 1 OF 2</b>

